



PMEG6002ELD-Q

40 V, 0.2 A low VF Schottky barrier rectifier

8 July 2024

Product data sheet

1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD882D (DFN1006D-2) leadless ultra small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 0.2$ A
- Reverse voltage: $V_R \leq 60$ V
- Low forward voltage: $V_F \leq 600$ mV
- Solderable side pads
- Package height typ. 0.37 mm
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- LED backlight for mobile application
- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Low power consumption applications

4. Quick reference data

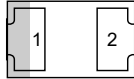

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20$ kHz; square wave; $T_{amb} \leq 130$ °C	-	-	0.2	A
		$\delta = 0.5$; $f = 20$ kHz; square wave; $T_{sp} \leq 140$ °C	-	-	0.2	A
V_R	reverse voltage	$T_j = 25$ °C	-	-	60	V
V_F	forward voltage	$I_F = 200$ mA; pulsed; $t_p \leq 300$ μ s; $\delta \leq 0.02$; $T_j = 25$ °C	-	540	600	mV
I_R	reverse current	$V_R = 10$ V; pulsed; $t_p \leq 2$ ms; $\delta \leq 0.02$; $T_j = 25$ °C	-	2	10	μ A

[1] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode ^[1]	 <p>Transparent top view</p> <p>DFN1006D-2 (SOD882D)</p>	 <p>sym001</p>
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

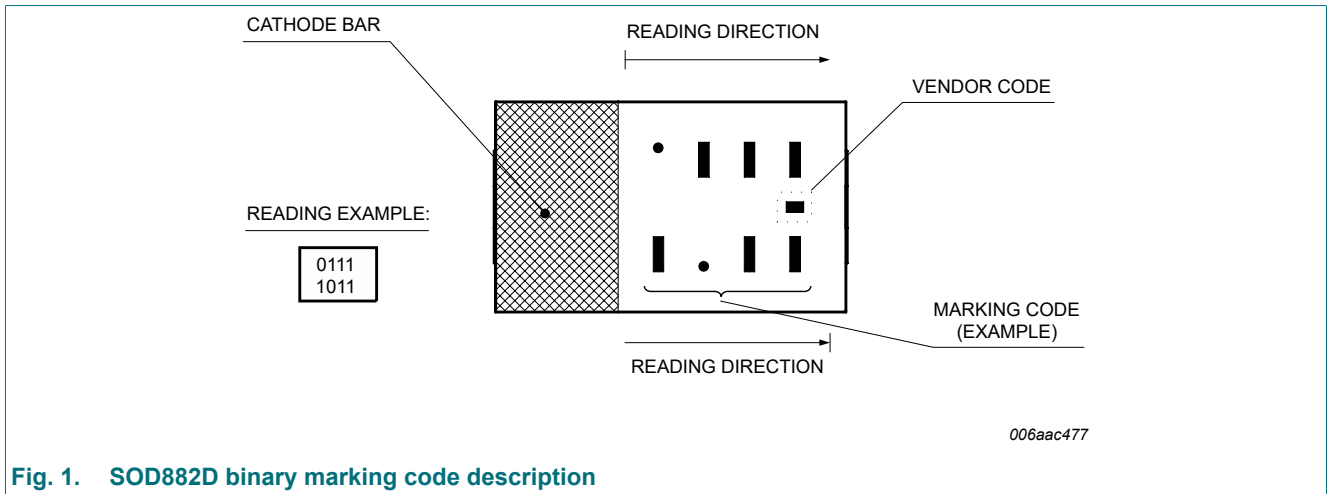
Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG6002ELD-Q	DFN1006D-2	leadless ultra small plastic package with side-wettable flanks (SWF); 2 terminals; 0.65 mm pitch; 1 mm x 0.6 mm x 0.4 mm body	SOD882D

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG6002ELD-Q	1111 1010



8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	$T_j = 25\text{ °C}$		-	60	V
I_F	forward current	$T_{sp} \leq 140\text{ °C}$		-	0.28	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{amb} \leq 130\text{ °C}$	[1]	-	0.2	A
		$\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{sp} \leq 140\text{ °C}$		-	0.2	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1\text{ ms}$; $\delta \leq 0.25$		-	1	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8\text{ ms}$; square wave; $T_{j(\text{init})} = 25\text{ °C}$		-	3	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2]	-	370	mW
			[3]	-	735	mW
			[1]	-	1090	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

[1] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	340	K/W
			[1] [3]	-	-	170	K/W
			[1] [4]	-	-	115	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	20	K/W

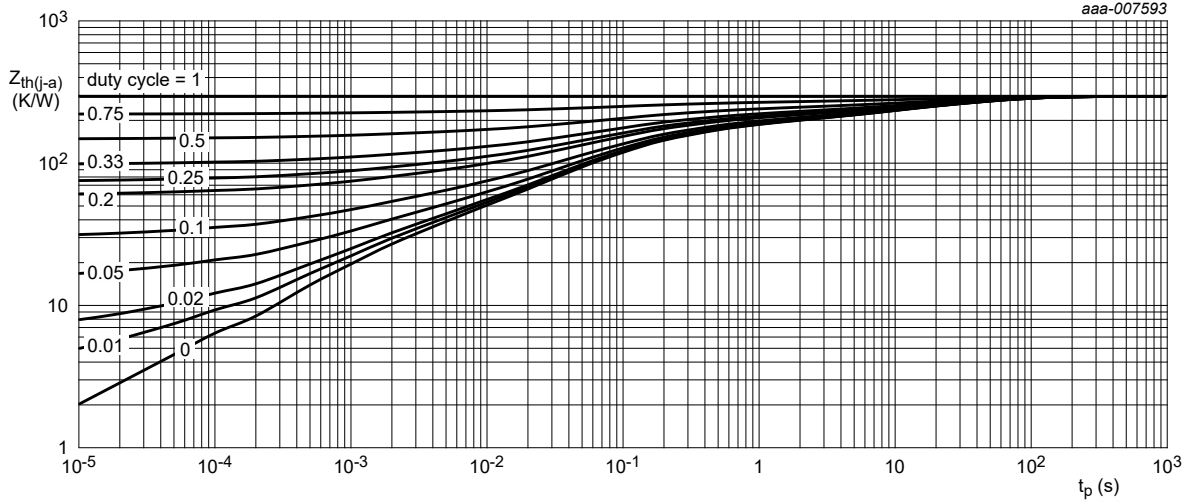
[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

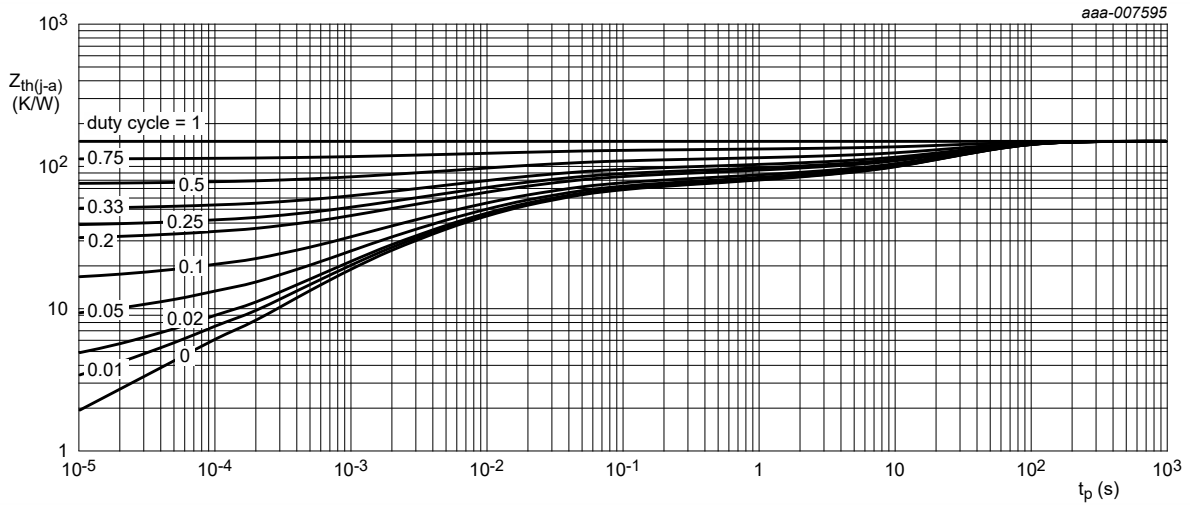
[4] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.

[5] Soldering point of cathode tab.



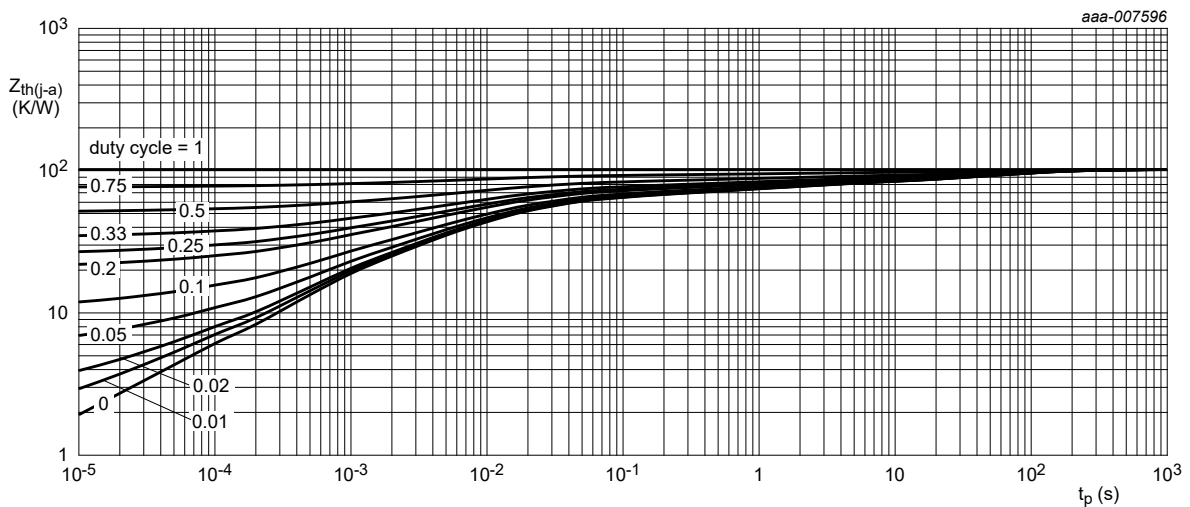
FR4 PCB, standard footprint

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm^2

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



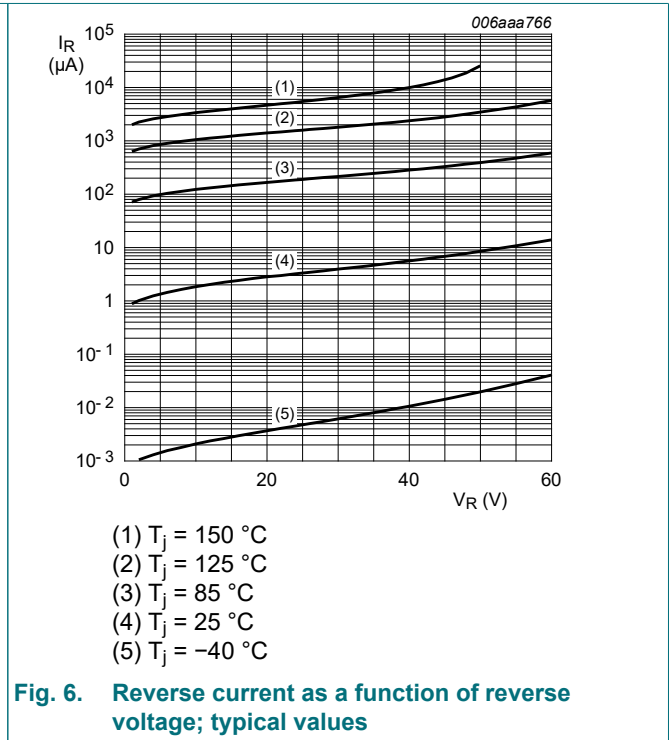
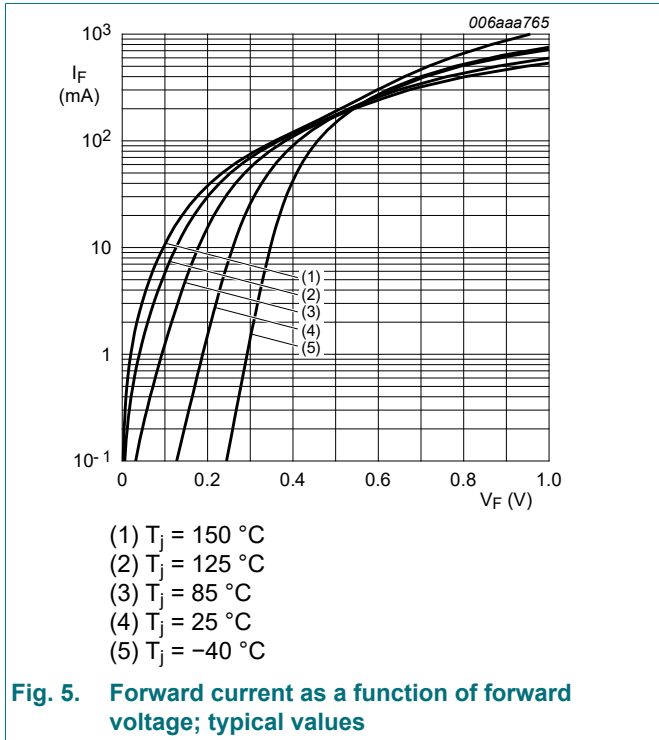
Ceramic PCB, Al_2O_3 , standard footprint

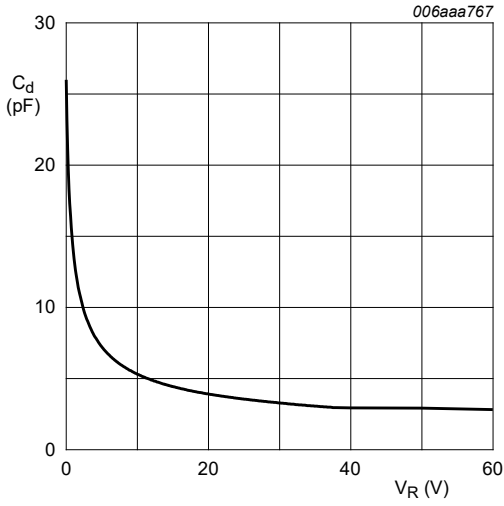
Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

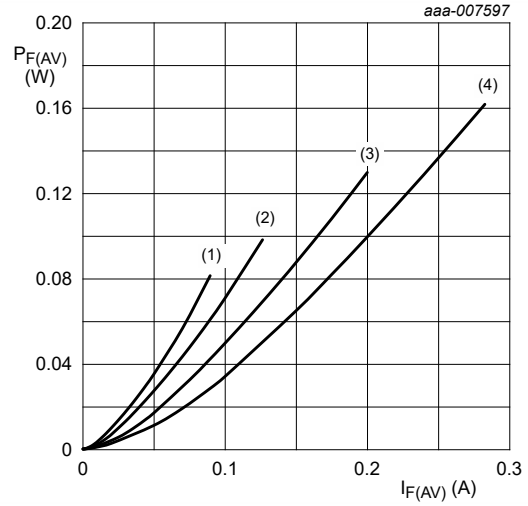
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 0.1 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ }^\circ\text{C}$	-	130	170	mV
		$I_F = 1 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ }^\circ\text{C}$	-	190	230	mV
		$I_F = 10 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ }^\circ\text{C}$	-	260	300	mV
		$I_F = 100 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ }^\circ\text{C}$	-	410	470	mV
		$I_F = 200 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_j = 25 \text{ }^\circ\text{C}$	-	540	600	mV
I_R	reverse current	$V_R = 10 \text{ V}$; pulsed; $t_p \leq 2 \text{ ms}$; $\delta \leq 0.02$; $T_j = 25 \text{ }^\circ\text{C}$	-	2	10	μA
		$V_R = 60 \text{ V}$; pulsed; $t_p \leq 2 \text{ ms}$; $\delta \leq 0.02$; $T_j = 25 \text{ }^\circ\text{C}$	-	20	100	μA
		$V_R = 10 \text{ V}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 100 \text{ }^\circ\text{C}$	-	310	-	μA
		$V_R = 60 \text{ V}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 100 \text{ }^\circ\text{C}$	-	2	-	mA
C_d	diode capacitance	$V_R = 1 \text{ V}$; $f = 1 \text{ MHz}$; $T_j = 25 \text{ }^\circ\text{C}$	-	15	20	pF
t_{rr}	reverse recovery time	$I_F = 10 \text{ mA}$; $I_R = 10 \text{ mA}$; $I_{R(\text{meas})} = 1 \text{ mA}$; $R_L = 100 \Omega$; $T_j = 25 \text{ }^\circ\text{C}$	-	4.5	-	ns





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

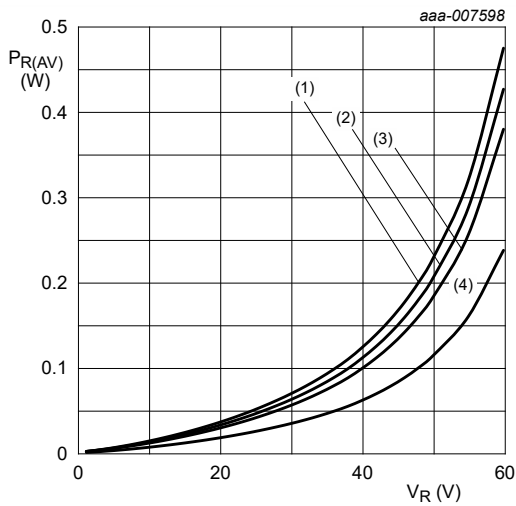
Fig. 7. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150 \text{ }^\circ\text{C}$

- (1) $\delta = 0.1; f = 20 \text{ kHz}$
- (2) $\delta = 0.2; f = 20 \text{ kHz}$
- (3) $\delta = 0.5; f = 20 \text{ kHz}$
- (4) $\delta = 1 \text{ (DC)}$

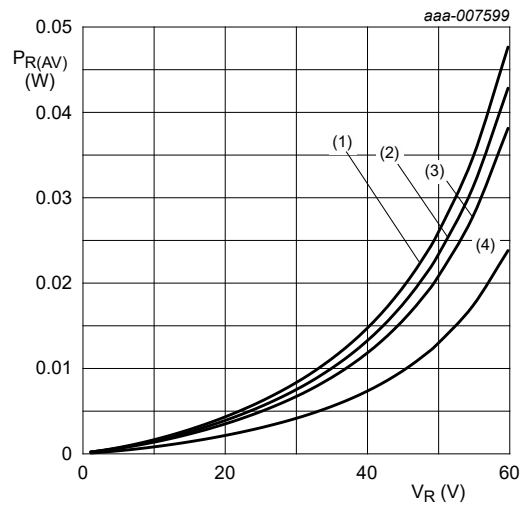
Fig. 8. Average forward power dissipation as a function of average forward current; typical values



$T_j = 125 \text{ }^\circ\text{C}$

- (1) $\delta = 1 \text{ (DC)}$
- (2) $\delta = 0.9; f = 20 \text{ kHz}$
- (3) $\delta = 0.8; f = 20 \text{ kHz}$
- (4) $\delta = 0.5; f = 20 \text{ kHz}$

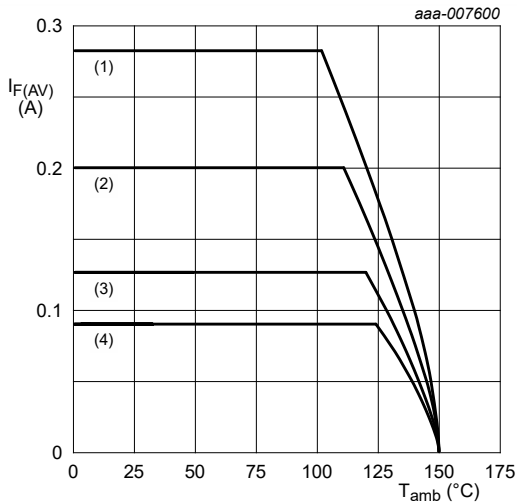
Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values



$T_j = 85 \text{ }^\circ\text{C}$

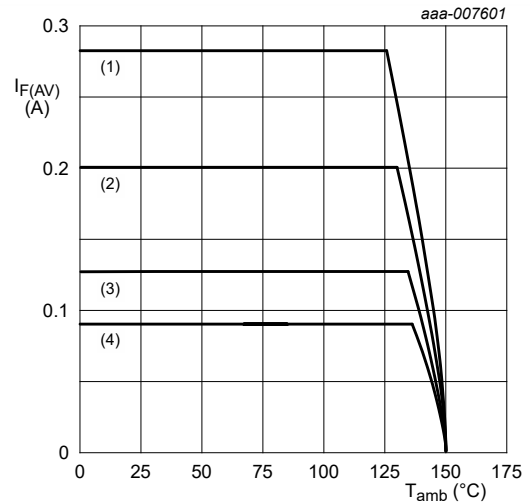
- (1) $\delta = 1 \text{ (DC)}$
- (2) $\delta = 0.9; f = 20 \text{ kHz}$
- (3) $\delta = 0.8; f = 20 \text{ kHz}$
- (4) $\delta = 0.5; f = 20 \text{ kHz}$

Fig. 10. Average reverse power dissipation as a function of reverse voltage; typical values



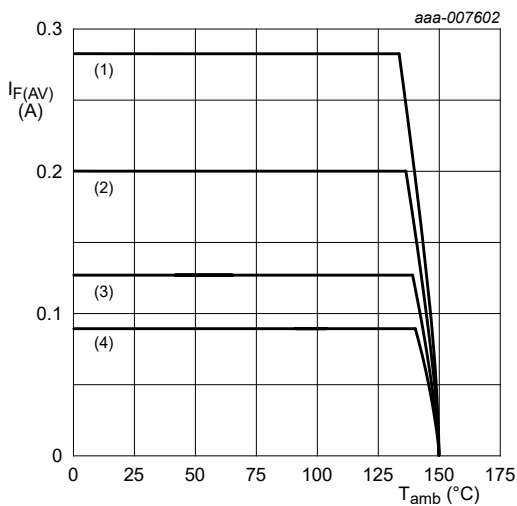
FR4 PCB, standard footprint
 $T_j = 150\text{ }^\circ\text{C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 11. Average forward current as a function of ambient temperature; typical values



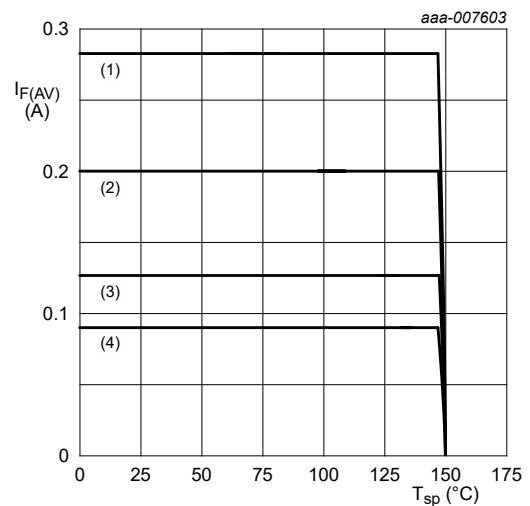
FR4 PCB, mounting pad for cathode 1 cm^2
 $T_j = 150\text{ }^\circ\text{C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 12. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al_2O_3 , standard footprint
 $T_j = 150\text{ }^\circ\text{C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 13. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ }^\circ\text{C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 14. Average forward current as a function of solder point temperature; typical values

11. Test information

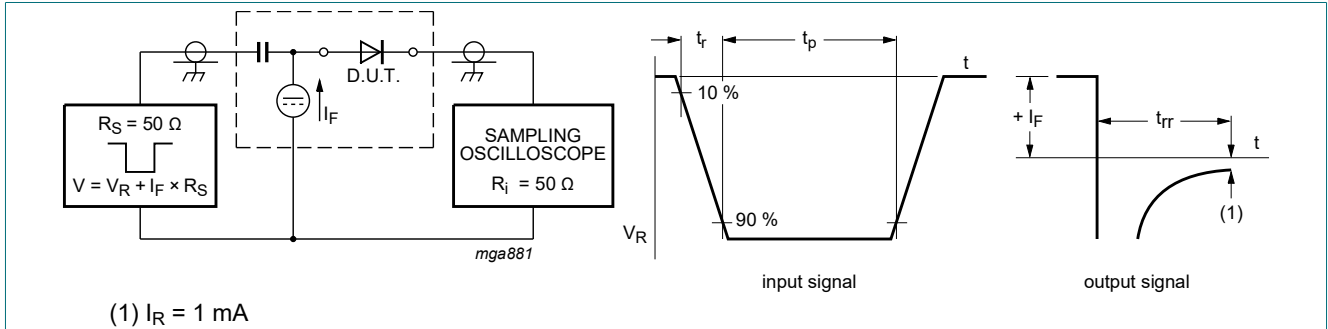


Fig. 15. Reverse recovery time: test circuit and waveforms

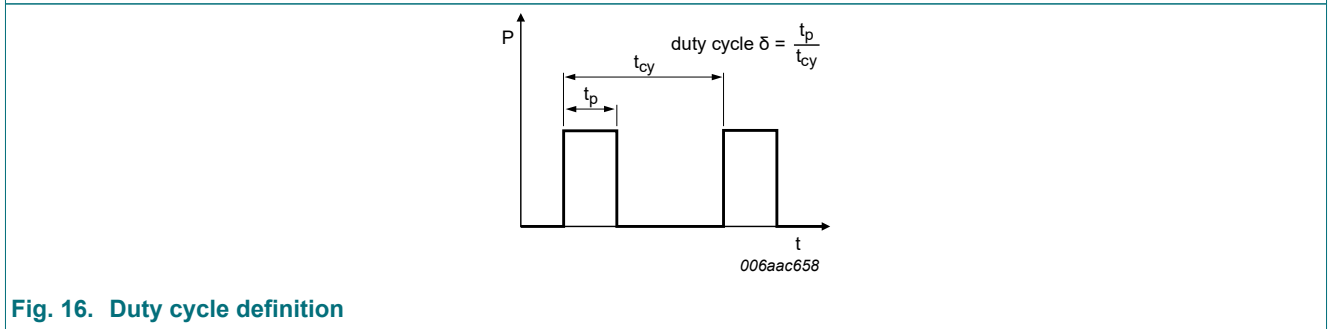


Fig. 16. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

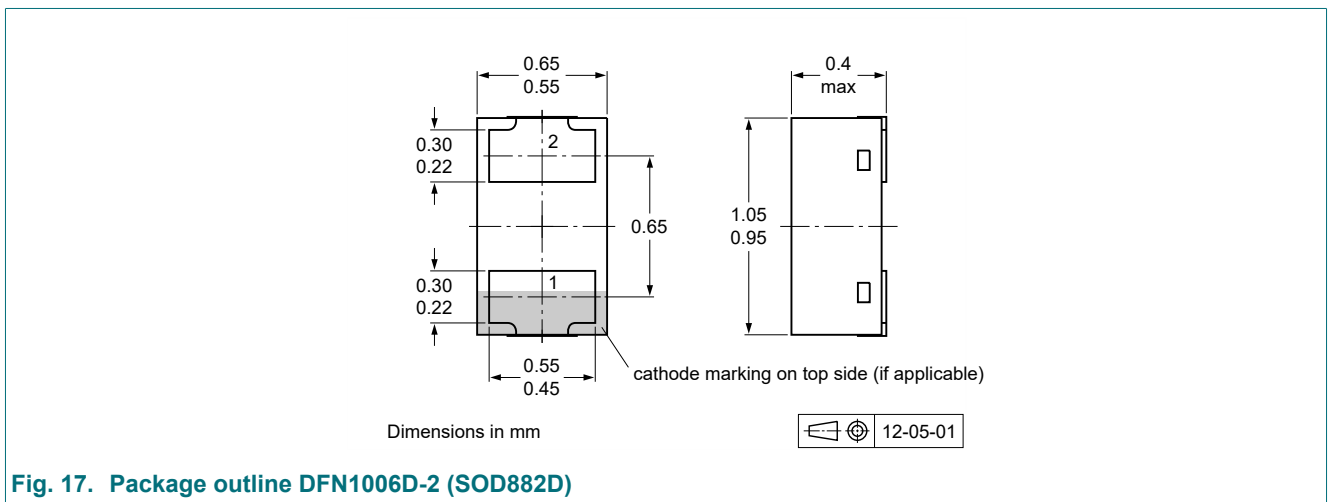


Fig. 17. Package outline DFN1006D-2 (SOD882D)

13. Soldering

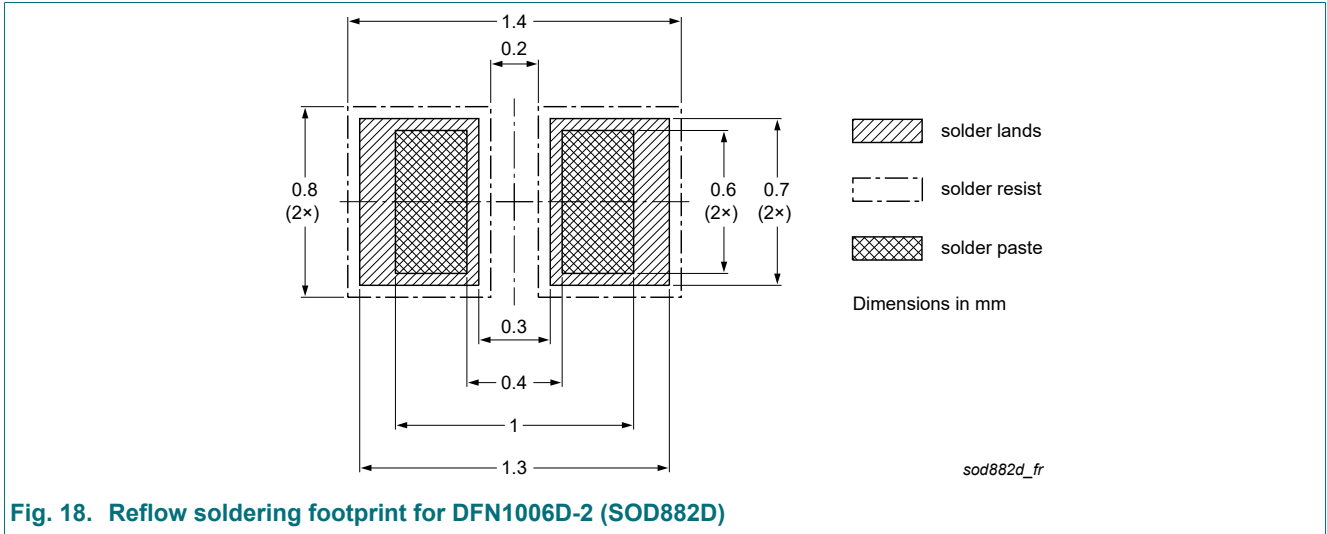


Fig. 18. Reflow soldering footprint for DFN1006D-2 (SOD882D)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG6002ELD-Q v.1	20240708	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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